

# NTZD3154N

## MOSFET – Dual, N-Channel, Small Signal

20 V, 540 mA

### Features

- Low  $R_{DS(on)}$  Improving System Efficiency
- Low Threshold Voltage
- Small Footprint 1.6 x 1.6 mm
- ESD Protected Gate
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Applications

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Management
- Cell Phones, Digital Cameras, PDAs, Pagers, etc.

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted.)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		$V_{DSS}$	20	V	
Gate-to-Source Voltage		$V_{GS}$	$\pm 7.0$	V	
Continuous Drain Current (Note 1)	Steady State	$I_D$	$T_A = 25^\circ\text{C}$	540	mA
			$T_A = 85^\circ\text{C}$	390	
Power Dissipation (Note 1)	Steady State		$P_D$	250	mW
Continuous Drain Current (Note 1)	$t \leq 5\text{ s}$	$I_D$	$T_A = 25^\circ\text{C}$	570	mA
			$T_A = 85^\circ\text{C}$	410	
Power Dissipation (Note 1)	$t \leq 5\text{ s}$		$P_D$	280	mW
Pulsed Drain Current	$t_p = 10\ \mu\text{s}$		$I_{DM}$	1.5	A
Operating Junction and Storage Temperature		$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$	
Source Current (Body Diode)		$I_S$	350	mA	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		$T_L$	260	$^\circ\text{C}$	

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient – Steady State (Note 1)	$R_{\theta JA}$	500	$^\circ\text{C/W}$
Junction-to-Ambient – $t \leq 5\text{ s}$ (Note 1)		447	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

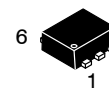
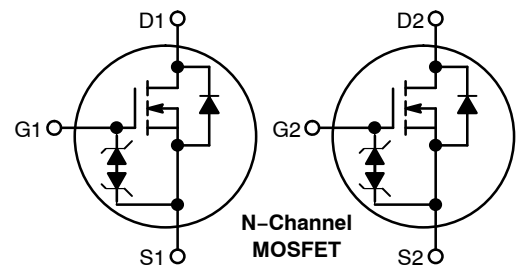
1. Surface mounted on FR4 board using 1 in sq pad size (Cu. area = 1.127 in sq [1 oz] including traces).



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$V_{(BR)DSS}$	$R_{DS(on)}$ Typ	$I_D$ Max (Note 1)
20	400 m $\Omega$ @ 4.5 V	540 mA
	500 m $\Omega$ @ 2.5 V	
	700 m $\Omega$ @ 1.8 V	



SOT-563-6  
CASE 463A

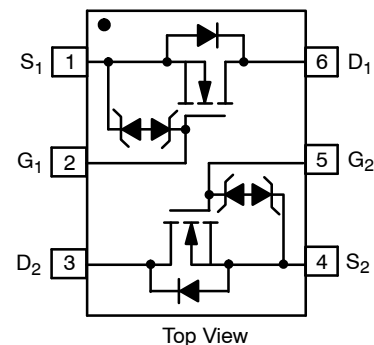
TV = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### MARKING DIAGRAM



### PINOUT: SOT-563



### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# NTZD3154N

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted.)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit	
<b>OFF CHARACTERISTICS</b>							
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	20	-	-	V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	-	-	14	-	mV/°C	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}$ $V_{DS} = 16\text{ V}$	$T_J = 25^\circ\text{C}$	-	-	1.0	$\mu\text{A}$
			$T_J = 125^\circ\text{C}$	-	-	5.0	
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 4.5\text{ V}$	-	-	$\pm 5.0$	$\mu\text{A}$	

## ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	0.45	-	1.0	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$	-	-	2.0	-	mV/°C
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 540\text{ mA}$	-	0.4	0.55	$\Omega$
		$V_{GS} = 2.5\text{ V}, I_D = 500\text{ mA}$	-	0.5	0.7	
		$V_{GS} = 1.8\text{ V}, I_D = 350\text{ mA}$	-	0.7	0.9	
Forward Transconductance	$g_{FS}$	$V_{DS} = 10\text{ V}, I_D = 540\text{ mA}$	-	1.0	-	S

## CHARGES AND CAPACITANCES

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = 16\text{ V}$	-	80	150	$\text{pF}$
Output Capacitance	$C_{OSS}$		-	13	25	
Reverse Transfer Capacitance	$C_{RSS}$		-	10	20	
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 10\text{ V}; I_D = 540\text{ mA}$	-	1.5	2.5	$\text{nC}$
Threshold Gate Charge	$Q_{G(TH)}$		-	0.1	-	
Gate-to-Source Charge	$Q_{GS}$		-	0.2	-	
Gate-to-Drain Charge	$Q_{GD}$		-	0.35	-	

## SWITCHING CHARACTERISTICS, $V_{GS} = V$ (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DD} = 10\text{ V}, I_D = 540\text{ mA},$ $R_G = 10\ \Omega$	-	6.0	-	ns
Rise Time	$t_r$		-	4.0	-	
Turn-Off Delay Time	$t_{d(OFF)}$		-	16	-	
Fall Time	$t_f$		-	8.0	-	

## DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V},$ $I_S = 350\text{ mA}$	$T_J = 25^\circ\text{C}$	-	0.7	1.2	V
			$T_J = 125^\circ\text{C}$	-	0.6	-	
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0\text{ V}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}, I_S = 350\text{ mA}$	-	6.5	-	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Surface-mounted on FR4 board using 1 in. sq. pad size (Cu. area = 1.127 in sq [1 oz] including traces).

3. Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES ( $T_J = 25^\circ\text{C}$  unless otherwise noted)

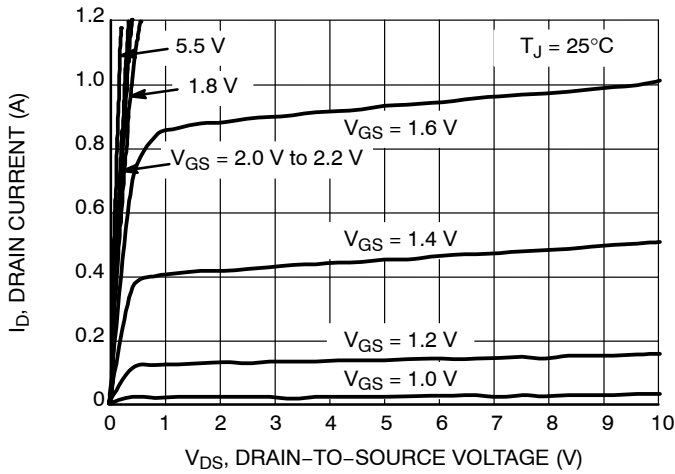


Figure 1. On-Region Characteristics

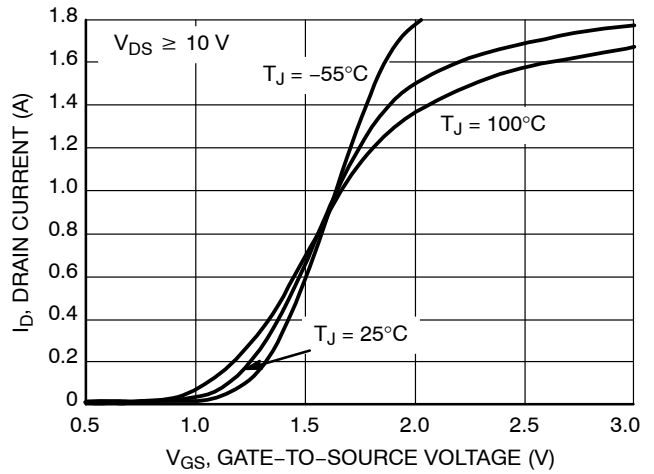


Figure 2. Transfer Characteristics

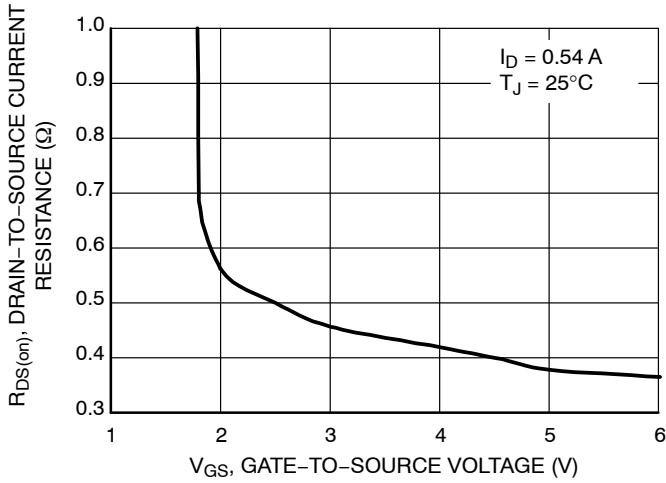


Figure 3. On-Resistance versus Gate-to-Source Voltage

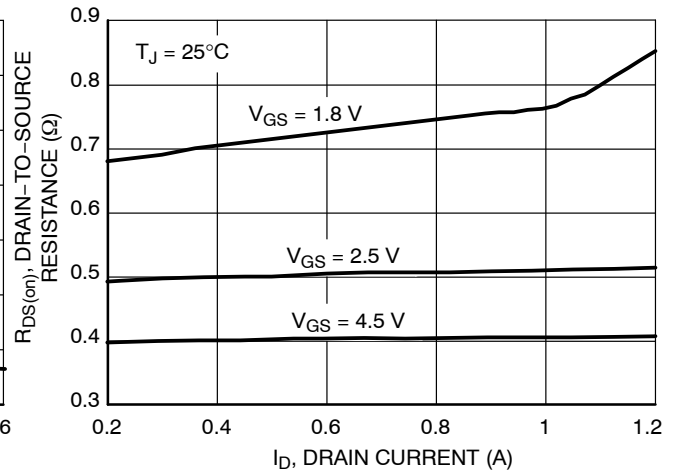


Figure 4. On-Resistance versus Drain Current and Gate Voltage

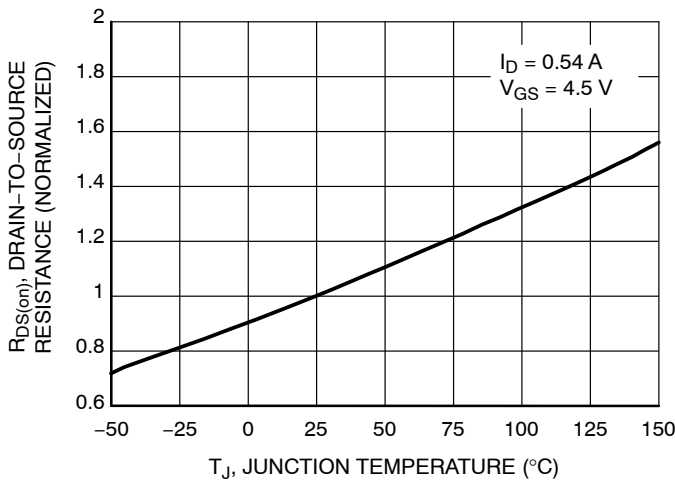


Figure 5. On-Resistance Variation with Temperature

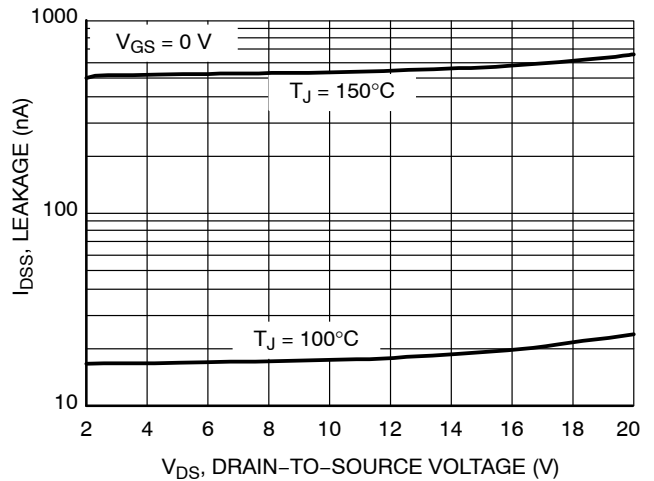


Figure 6. Drain-to-Source Leakage Current versus Voltage

# NTZD3154N

## TYPICAL PERFORMANCE CURVES ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

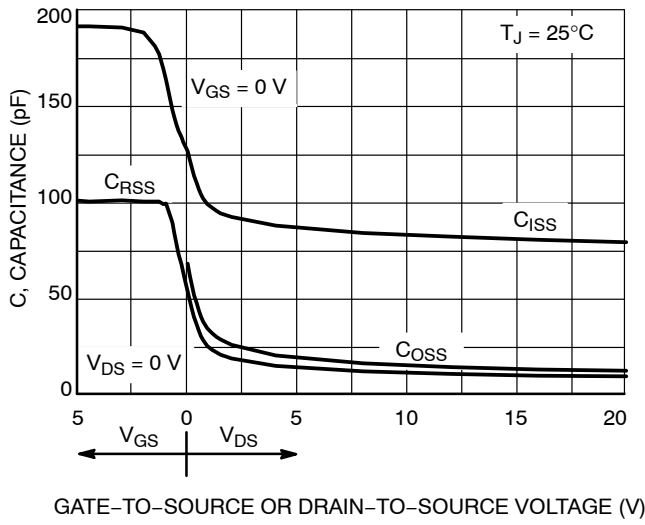


Figure 7. Capacitance Variation

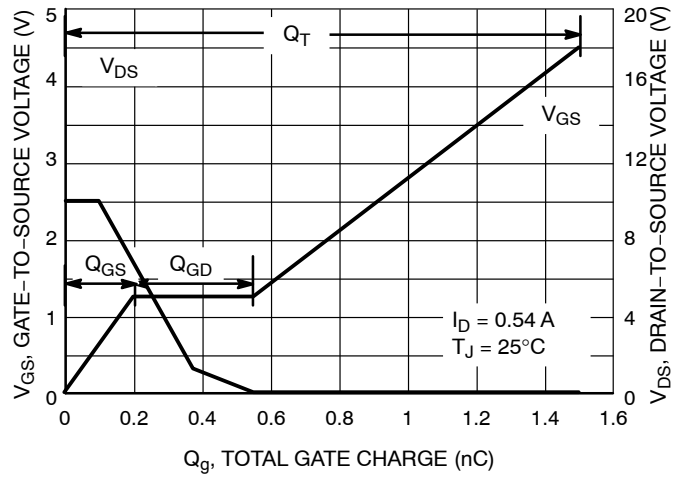


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

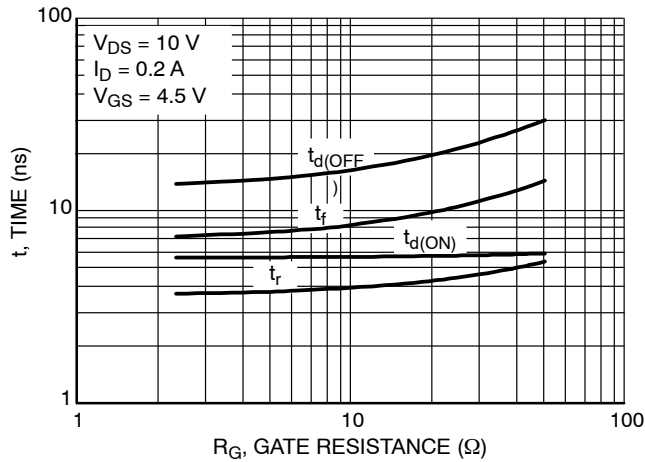


Figure 9. Resistive Switching Time Variation versus Gate Resistance

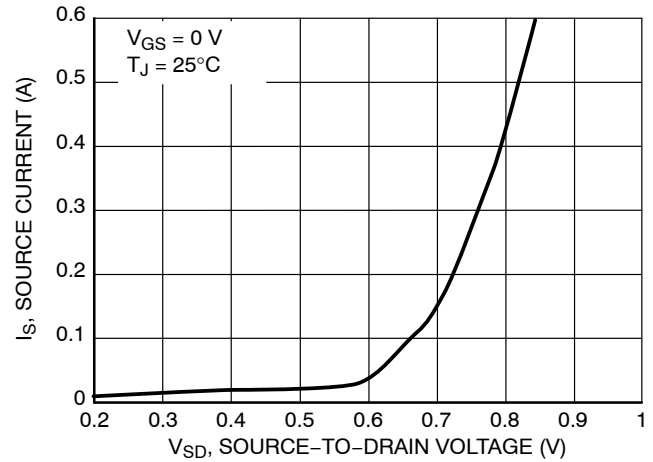


Figure 10. Diode Forward Voltage versus Current

### ORDERING INFORMATION

Device	Package	Shipping
NTZD3154NT1G	SOT-563 (Pb-Free)	4000 / Tape & Reel
NTZD3154NT1H		
NTZD3154NT2G		
NTZD3154NT2H		
NTZD3154NT5G		8000 / Tape & Reel
NTZD3154NT5H		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

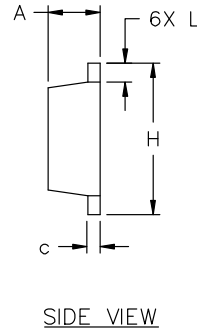
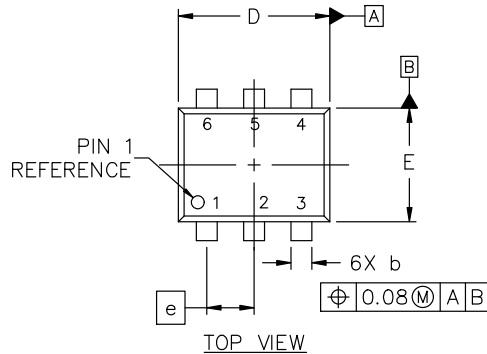


**SOT-563-6 1.60x1.20x0.55, 0.50P**  
**CASE 463A**  
**ISSUE J**

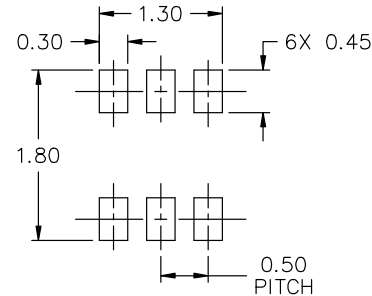
DATE 15 FEB 2024

**NOTES:**

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
b	0.17	0.22	0.27
c	0.08	0.13	0.18
D	1.50	1.60	1.70
E	1.10	1.20	1.30
e	0.50 BSC		
H	1.50	1.60	1.70
L	0.10	0.20	0.30



**STYLE 1:**  
 PIN 1. EMITTER 1  
 2. BASE 1  
 3. COLLECTOR 2  
 4. EMITTER 2  
 5. BASE 2  
 6. COLLECTOR 1

**STYLE 2:**  
 PIN 1. EMITTER 1  
 2. EMITTER 2  
 3. BASE 2  
 4. COLLECTOR 2  
 5. BASE 1  
 6. COLLECTOR 1

**STYLE 3:**  
 PIN 1. CATHODE 1  
 2. CATHODE 1  
 3. ANODE/ANODE 2  
 4. CATHODE 2  
 5. CATHODE 2  
 6. ANODE/ANODE 1

**STYLE 4:**  
 PIN 1. COLLECTOR  
 2. COLLECTOR  
 3. BASE  
 4. EMITTER  
 5. COLLECTOR  
 6. COLLECTOR

**STYLE 5:**  
 PIN 1. CATHODE  
 2. CATHODE  
 3. ANODE  
 4. ANODE  
 5. CATHODE  
 6. CATHODE

**STYLE 6:**  
 PIN 1. CATHODE  
 2. ANODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE

**STYLE 7:**  
 PIN 1. CATHODE  
 2. ANODE  
 3. CATHODE  
 4. CATHODE  
 5. ANODE  
 6. CATHODE

**STYLE 8:**  
 PIN 1. DRAIN  
 2. DRAIN  
 3. GATE  
 4. SOURCE  
 5. DRAIN  
 6. DRAIN

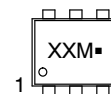
**STYLE 9:**  
 PIN 1. SOURCE 1  
 2. GATE 1  
 3. DRAIN 2  
 4. SOURCE 2  
 5. GATE 2  
 6. DRAIN 1

**STYLE 10:**  
 PIN 1. CATHODE 1  
 2. N/C  
 3. CATHODE 2  
 4. ANODE 2  
 5. N/C  
 6. ANODE 1

**STYLE 11:**  
 PIN 1. EMITTER 2  
 2. BASE 2  
 3. COLLECTOR 1  
 4. EMITTER 1  
 5. BASE 1  
 6. COLLECTOR 2

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



XX = Specific Device Code  
 M = Month Code  
 ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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